# Heraeus

## 3571

### Conductor

#### Description

3571 is a high performance silver conductor designed for cost sensitive hybrid applications. 3571 employs advanced powders technology with a mix bonded frit system to yield a highly dense fired film that is resistant to solder leaching. 3571 also exhibits excellent adhesion to Beryllium Oxide (BeO) substrates.

#### **Key Features**

- Dense fired film
- Designed for cost sensitive hybrid applications
- Exhibits excellent adhesion to beryllium oxide substrates



This picture does not show the packaging of 3571 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties				
Viscosity	170-200 kcps, Brookfield HBT, SC4-14 spindle and 6R utility cup at 10 rpm, 25°C			
Alloy Ratio	100			
Coverage	70-75 cm 2/gm (Calculated from 50 micron wet film)			
Metal	Ag			
Color	Silver			
Recommended Processing Guide				
Process Temperature (TDS)	850°C peak temperature. Dwell time of 5- 10 minutes at peak. Firing range of 850°C to 925°C possible with minimal differences in properties.			
Film Thickness	9 -15 um			

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#### Warranty

6 months

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